

SOT761-1

plastic thin fine-pitch ball grid array package; 72 balls; body
6 x 6 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA72
Package type industry code	TFBGA72
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	10-4-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	0.75	-	0.8	0.85	mm
n ₂	actual quantity of termination	-	-	72	-	



2. Package outline

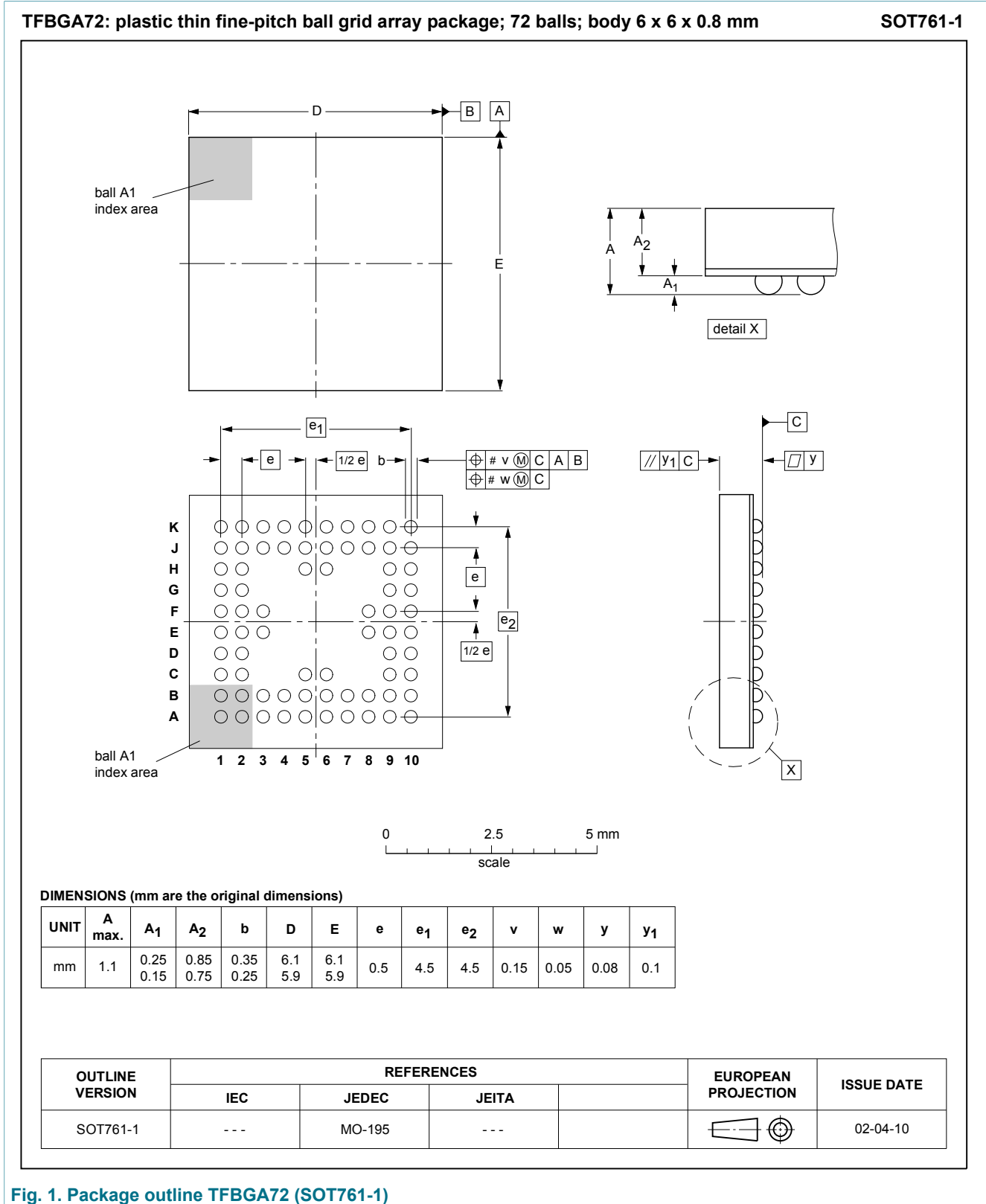
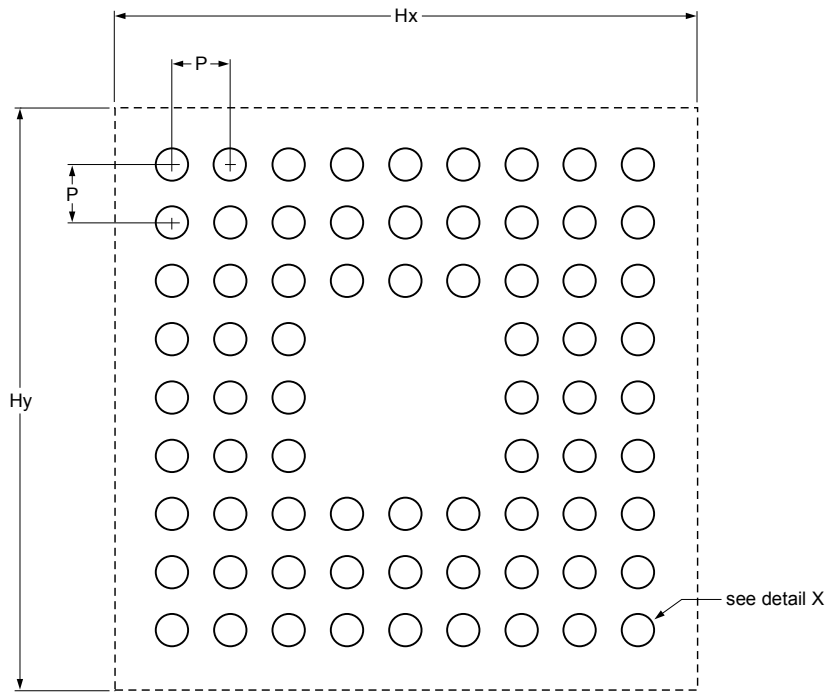


Fig. 1. Package outline TFBGA72 (SOT761-1)




3. Soldering

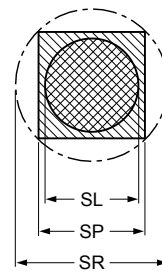
Footprint information for reflow soldering of TFBGA72 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	6.500	6.500

sot761-1_fr

Fig. 2. Reflow soldering footprint for TFBGA72 (SOT761-1)

4. Legal information

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